

# TECHNICAL DATA SHEET

"K"-85 COG dielectric

"LF-085"

LF-085 is an environmentally friendly low fire high dielectric constant COG dielectric. It contains a low percentage of bismuth-based compounds, but is not formulated with lead or cadmium. LF-085 is an excellent choice for range extension of COG products.

## **Key Features**

400

- Environmentally friendly (RoHS compliant)
- Dielectric constant of 75 to 95
- Compatible with up to 75% Ag / 25% Pd electrode systems
- Excellent lot to lot uniformity

#### **Typical powder properties**

■ Powder density, g/cm³	≥ <b>5.25</b>
■ Surface area, m²/g	2.40 ± 1.00

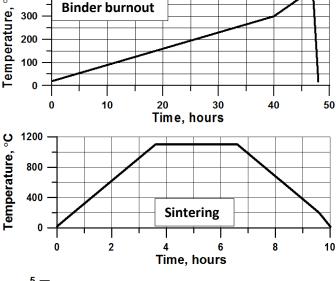
■ Particle size, µm

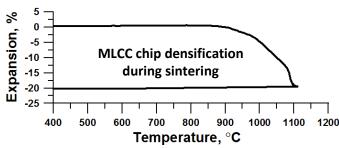
$D_{90}$	≤ 4.00
D <sub>50</sub>	0.70 ± 0.25
D <sub>10</sub>	0.35 ± 0.10
6 hours) %	< 0.70

■ LOI (650°C, 6 hours), % ≤ 0.70

## **Sintering conditions**

- Binder burnout up to 400°C in air
- Sintering 1100°C ± 20°C/3 hours in air
- Heating rate 5°C/min
- Open ZrO<sub>2</sub> setter
- Fired density ≥ 5.40 g/cm<sup>3</sup>

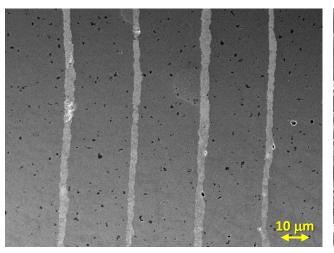


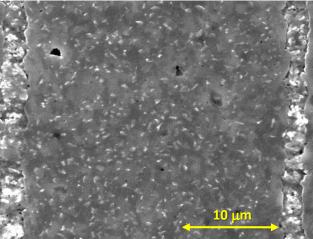


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#### Typical cross-sectional microstructure of sintered MLCC chip





#### Mechanical properties of the dielectric

 Coefficient of thermal expansion from 200°C to 600°C, μm/m\*K
 8.9

### Typical MLCC characteristics

■ Chip size	0805
Active layers	10.5
Electrode: 75% Ag / 25% Pd	
■ Dielectric thickness, µm	~20
■ Dielectric constant	85 ± 10
Dissipation factor, %	≤ 0.02 @
	1kHz, 1Vrms
	<b>≤ 0.10</b> @
	1MHz,1Vrms
Insulation resistance at 300V	
and 125°C, Ω	> 10 <sup>11</sup>
<ul><li>Dielectric withstanding</li></ul>	
voltage, V/μm	≥ 60

## Temperature variation of capacitance

TCC COG (±30ppm/°C from -55°C to +125°C)

The data presented is based on our research and is considered to be fair representation of this product.

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